

EMK23G2J-25.117M TR [Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on Mar 1, 2017)



◀ Click badges to download compliance docs

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



ITEM DESCRIPTION

MEMS Clock Oscillators LVCMOS (CMOS) 3.3Vdc 4 Pad 3.2mm x 5.0mm Plastic Surface Mount (SMD) 25.117MHz ±100ppm over -40°C to +85°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	25.117MHz
Frequency Tolerance/Stability	±100ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, 260°C Reflow, Shock, and Vibration)
Aging at 25°C	±1ppm Maximum First Year
Supply Voltage	3.3Vdc ±10%
Input Current	25mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH=-8mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL=+8mA)
Rise/Fall Time	2nSec Maximum (Measured from 20% to 80% of waveform)
Duty Cycle	50 ±5(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Power Down (Disabled Output: Logic Low)
Output Control Input Voltage	+0.7Vdd Minimum or No Connect to Enable Output, +0.3Vdd Maximum to Disable Output
Standby Current	50µA Maximum (Disabled Output: Logic Low)
Peak to Peak Jitter (tPK)	250pSec Maximum, 100pSec Typical
Start Up Time	50mSec Maximum
Storage Temperature Range	-55°C to +125°C

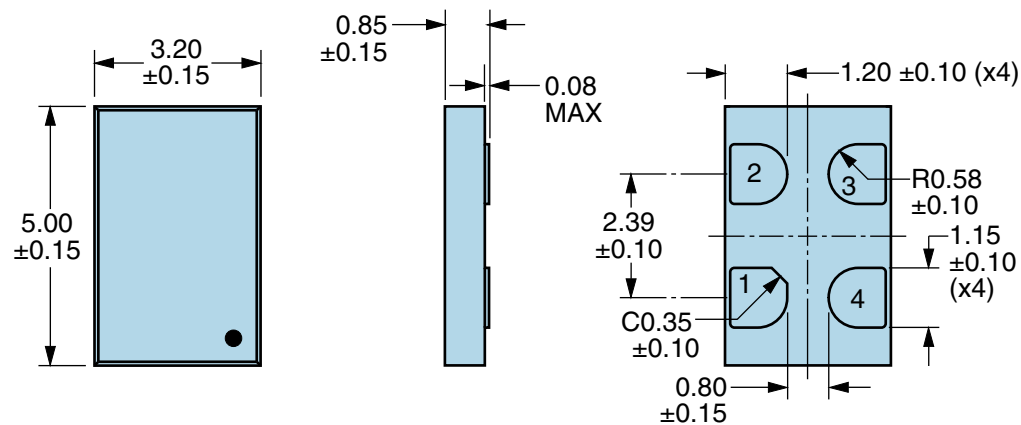
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 2, HBM 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition G, 30,000G
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity Level	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003 (Pads on bottom of package only)
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Thermal Shock	MIL-STD-883, Method 1011, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

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MECHANICAL DIMENSIONS (all dimensions in millimeters)

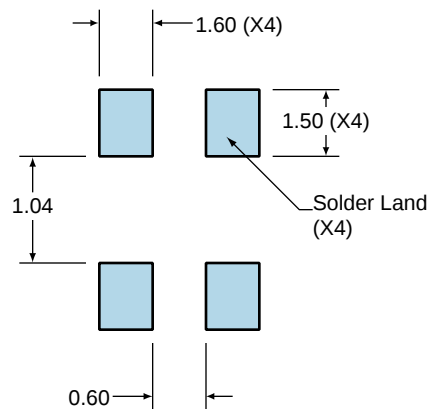


PIN	CONNECTION
1	Power Down
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	XXXX or XXXXX XXXX or XXXXX=Ecliptek Manufacturing Lot Code

Suggested Solder Pad Layout

All Dimensions in Millimeters

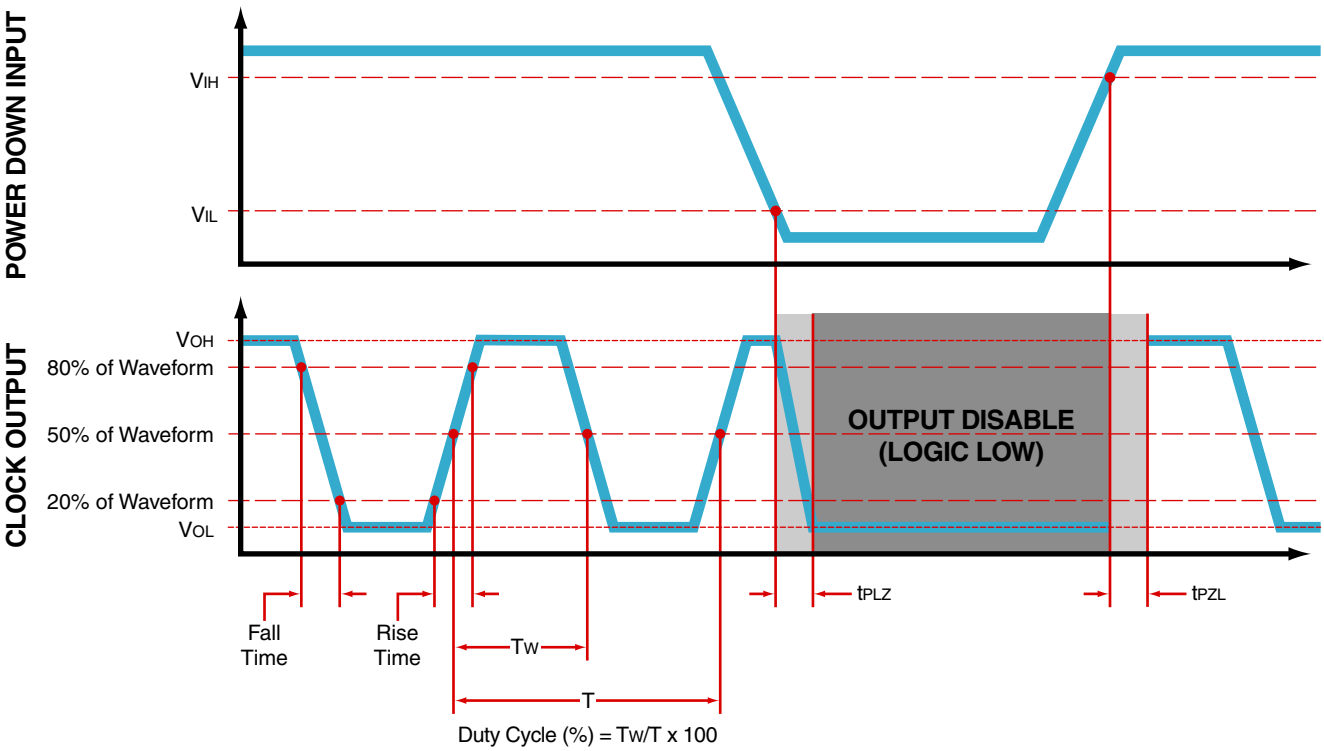


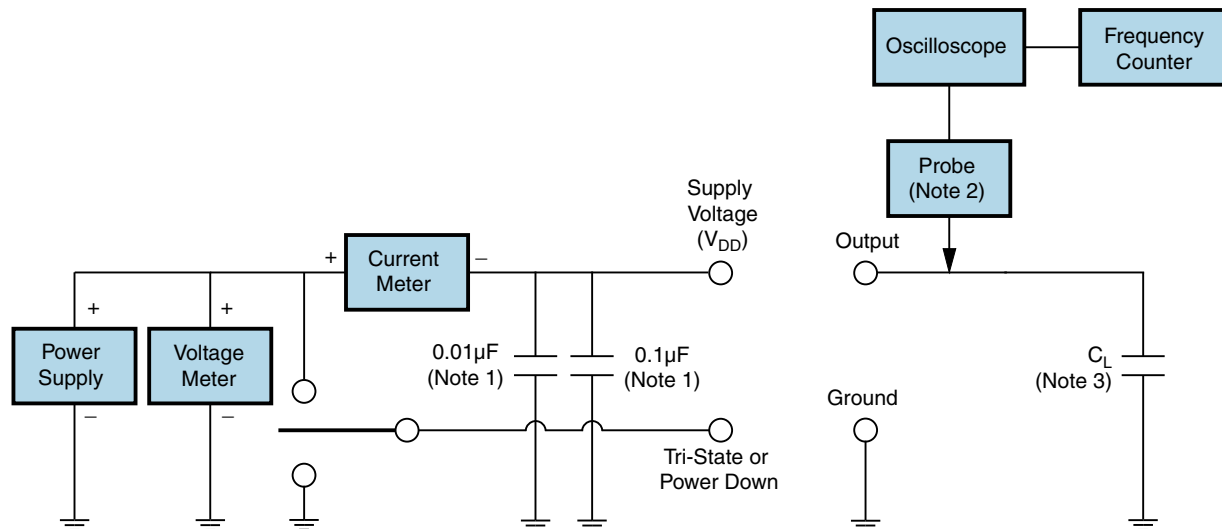
All Tolerances are ±0.1

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OUTPUT WAVEFORM & TIMING DIAGRAM



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Note 1: An external $0.01\mu\text{F}$ ceramic bypass capacitor in parallel with a $0.1\mu\text{F}$ high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance ($<12\text{pF}$), 10X Attenuation Factor, High Impedance ($>10\text{Mohms}$), and High bandwidth ($>300\text{MHz}$) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

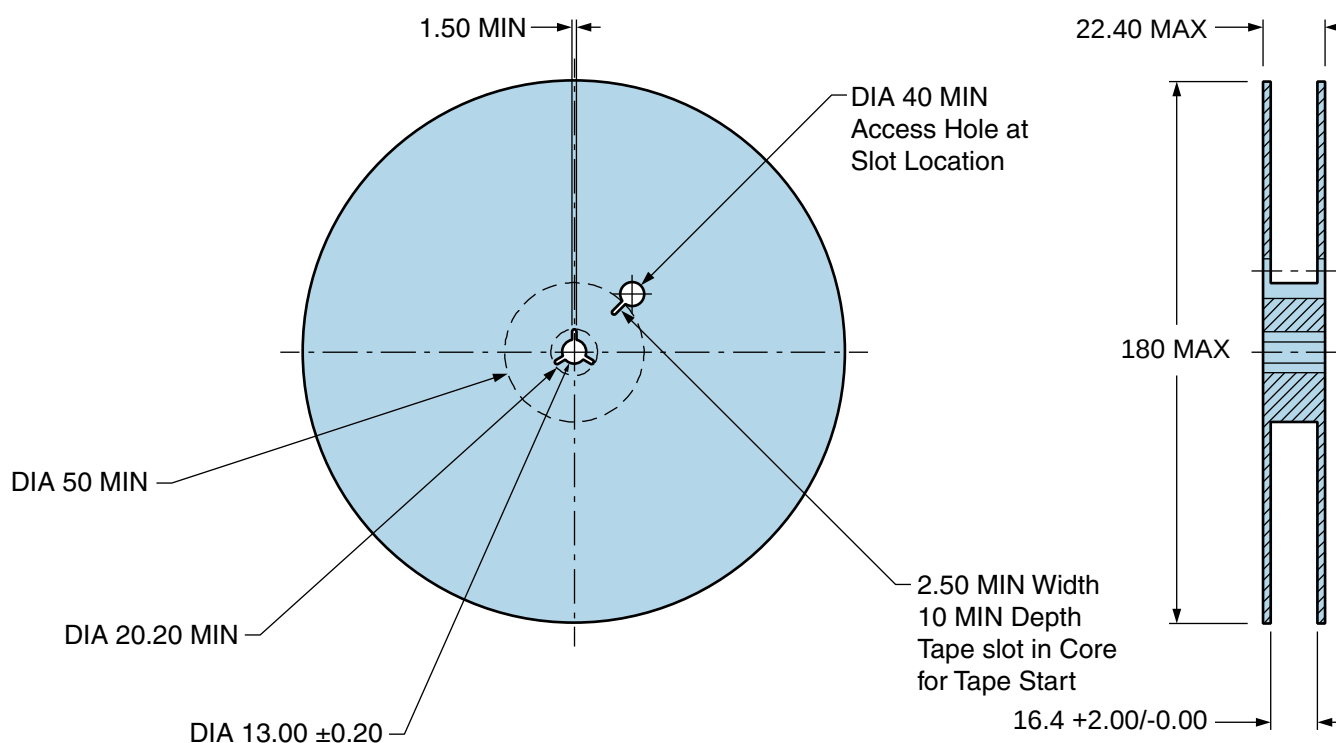
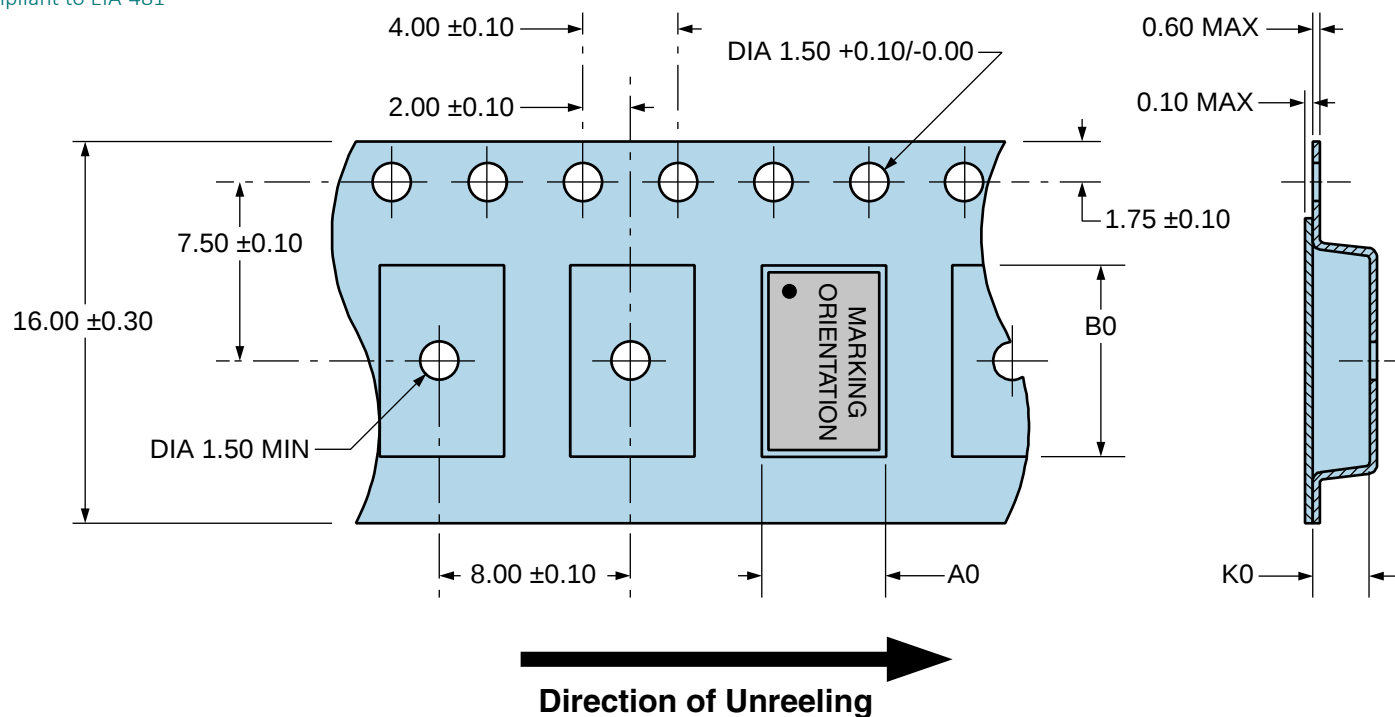
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Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



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Recommended Solder Reflow Methods



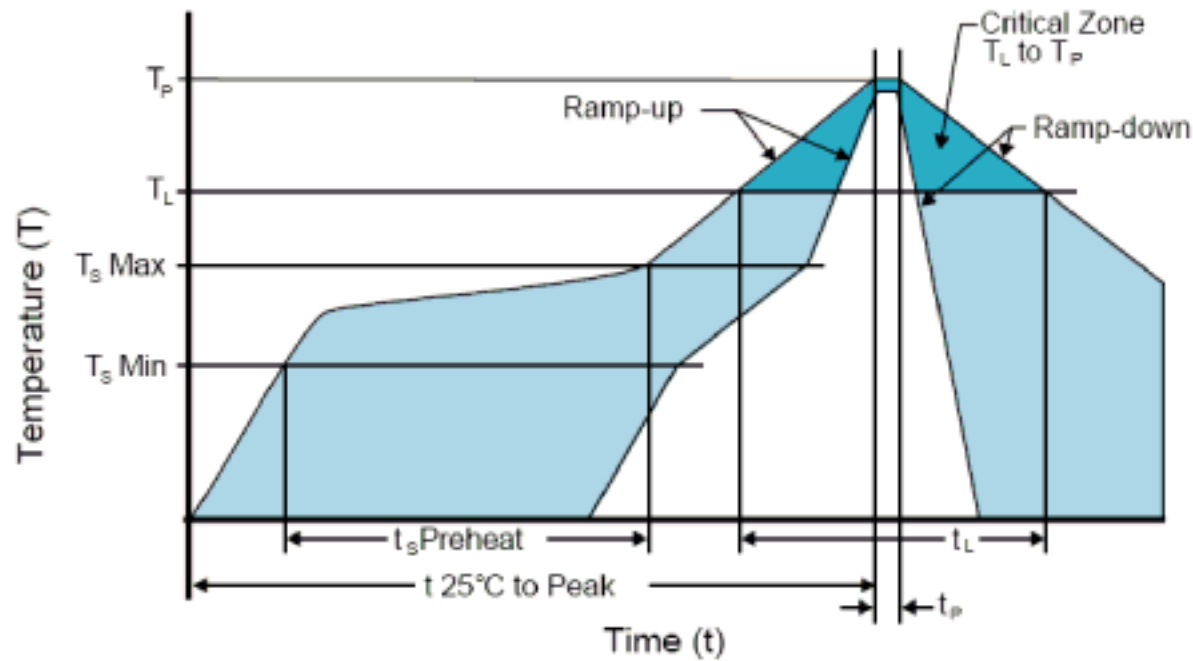
High Temperature Infrared/Convection

Ts MAX to TL (Ramp-up Rate)		3°C/Second Maximum
Preheat		
- Temperature Minimum (Ts MIN)		150°C
- Temperature Typical (Ts TYP)		175°C
- Temperature Maximum (Ts MAX)		200°C
- Time (ts MIN)		60 - 180 Seconds
Ramp-up Rate (TL to TP)		3°C/Second Maximum
Time Maintained Above:		
- Temperature (TL)		217°C
- Time (tL)		60 - 150 Seconds
Peak Temperature (TP)		260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (TP Target)		250°C +0/-5°C
Time within 5°C of actual peak (tp)		20 - 40 Seconds
Ramp-down Rate		6°C/Second Maximum
Time 25°C to Peak Temperature (t)		8 Minutes Maximum
Moisture Sensitivity Level		Level 1
Additional Notes		Temperatures shown are applied to body of device.

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	240°C Maximum
Target Peak Temperature (TP Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tP)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)